Cryptographic Hardware and Embedded Systems (CHES)
CHES 2023 in Prague, Czech Republic, September, 2023
IACR Transactions on CHES (TCHES), Volume 2023, Issues 1–4

Call for Papers

Having been established in 1999, the Cryptographic Hardware and Embedded Systems (CHES) conference is the premier venue for research on both design and analysis of cryptographic hardware and software implementations. As an area conference of the International Association for Cryptologic Research (IACR), CHES bridges the cryptographic research and engineering communities, and attracts participants from academia, industry, government and beyond. CHES 2023 will take place in Prague, Czech Republic, in September 2023. The conference website is accessible at

https://ches.iacr.org/2023

The scope of CHES is intentionally diverse, meaning we solicit submission of papers on topics including, but not limited to, the following (with new topics for CHES 2023 highlighted in bold blue):

Cryptographic implementations:
- Hardware architectures
- Cryptographic processors and coprocessors
- True and pseudorandom number generators
- Physical unclonable functions (PUFs)
- Efficient software implementations

Attacks against implementations, and countermeasures:
- Remote, micro-architectural and physical side-channel attacks and countermeasures
- Fault attacks and countermeasures
- Hardware tampering and tamper-resistance
- White-box cryptography and code obfuscation
- Reverse engineering of hardware/software

Tools and methodologies:
- Formal methods, techniques and tools for secure design and verification for hardware/software
- Computer aided cryptographic engineering
- Domain-specific languages for cryptographic systems
- Metrics for the security of embedded systems
- FPGA design security

Systematization of Knowledge (SoK)

Interactions between cryptographic theory and implementation issues:
- Quantum cryptanalysis
- Algorithm subversion and subversion prevention
- New and emerging cryptographic algorithms and protocols targeting embedded devices
- Special-purpose hardware for cryptanalysis, including quantum circuits
- Leakage resilient cryptography

Applications:
- RISC-V security
- Trusted execution environments and trusted computing platforms
- IP protection for hardware/software and technologies for anti-counterfeiting
- Reconfigurable hardware for cryptography
- Secure elements, security subsystems, and applications
- Security for the Internet of Things and cyberphysical systems (RFID, sensor networks, smart meters, medical implants, smart devices for home automation, industrial control, automotive, etc.)
- Secure storage devices (memories, disks, etc.)
- **Isolation and monitoring hardware for cyber-resilience**
- **Engineering of zero-knowledge proof systems**
- **Privacy-preserving computing in practice (MPC, FHE)**

TCHES Publication Model

CHES has transitioned to an open-access journal/conference hybrid model. A comprehensive list of FAQs relating to the model can be found via the TCHES website at

https://tches.iacr.org

In summary:

1. Submitted papers will undergo a journal-style review process, with accepted papers published by Ruhr University Bochum in an issue of the journal IACR Transactions on Cryptographic Hardware and Embedded Systems (TCHES). Since it has a Gold Open Access status, all papers published in TCHES are immediately and freely available.

2. The annual CHES conference consists of presentations for each paper published in the associated issues of TCHES, plus invited talks and a range of additional and social activities. All papers accepted for publication in TCHES between 15 July of year $n-1$ and 15 July of year n will be presented at CHES of year n.

Timeline

TCHES has four submission deadlines per year; Upcoming deadlines relating to CHES 2023 are as follows:

- IACR Transactions on Cryptographic Hardware and Embedded Systems (TCHES), Volume 2023, Issue 1
    - Submission: **15 July 2022**
    - Rebuttal: 22–26 August 2022
    - Notification: 15 September 2022
    - Camera-ready: 14 October 2022

- IACR Transactions on Cryptographic Hardware and Embedded Systems (TCHES), Volume 2023, Issue 2
    - Submission: **15 October 2022**
    - Rebuttal: 21–25 November 2022
    - Notification: 15 December 2022
    - Camera-ready: 14 January 2023

- IACR Transactions on Cryptographic Hardware and Embedded Systems (TCHES), Volume 2023, Issue 3
    - Submission: **15 January 2023**
    - Rebuttal: 20–24 February 2023
    - Notification: 15 March 2023
    - Camera-ready: 14 April 2023

- IACR Transactions on Cryptographic Hardware and Embedded Systems (TCHES), Volume 2023, Issue 4
    - Submission: **15 April 2023**
    - Rebuttal: 22–26 May 2023
    - Notification: 15 June 2023
    - Camera-ready: 14 July 2023

The camera-ready deadline relates to accepted and conditionally accepted papers. *All* deadlines are 23:59:59 Anywhere on Earth (AoE).

Instructions for Authors

1. Format

A paper submitted to TCHES must be written in English and be anonymous, with no author names, affiliations, acknowledgments, or any identifying citations. It should begin with a title, a short abstract, and a list of keywords. The introduction should summarize the contributions of the paper at a level appropriate for a non-specialist reader. Submissions should be typeset in the LaTeX style available at

<div align="center">

https://tches.iacr.org/index.php/TCHES/submission,

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noting that TCHES only accepts electronic submission in PDF format. Please use the submission mode (\documentclass[submission]{iacrtrans}) that displays line numbers to ease the review process.

TCHES accepts two forms of paper, termed short and long; the page limit (excluding bibliography) is 20 and 40 pages respectively. Authors are encouraged to include additional supplementary material needed to validate the content (e.g., test vectors or source code) as separate files. **In order to ensure that appendices are also reviewed, they need to be included *before* the bibliography within the 20 or 40-page limit during submission.** In allowing long papers, the goal is to support cases where extra detail (e.g., proofs, or experimental results) is deemed essential. Long papers need to be marked as such by checking the respective box in the submission system and by annotating the title with *Long Paper:*. **Authors need to justify the need to submit the content as long paper in a justification letter included in the supplementary materials.** Long papers submitted without proper justification will be returned without review. Authors of long papers should be aware that the review process may take longer: a decision may, at the discretion of the editor(s)-in-chief, be deferred to the subsequent volume.

TCHES solicits submission of Systematization of Knowledge (SoK) papers, i.e., papers whose goal is to review and contextualize existing literature in a particular area in order to systematize existing knowledge. To be considered for publication, SoK papers must provide significant added value beyond prior work, such as novel insights or reasonably questioning previous assumptions. Authors should highlight SoK papers by annotating the title with *SoK:*.

2. Regulations

The review process for TCHES, Volume 2023, Issues 1–4, will be governed by the following regulations:

- TCHES follows IACR policy, i.e.,

    https://www.iacr.org/docs/irregular.pdf

    with respect to irregular submissions: any submission deemed to be irregular (e.g., which has been submitted, in parallel, to another conference with proceedings), will be instantly rejected. IACR reserves the right to share information about submissions with other program committees and editorial boards to ensure strict enforcement of the policy.

- TCHES follows IACR policy with respect to conflicts of interest that could prevent impartial review. A conflict of interest is considered to occur automatically whenever one (co-)author of a submitted paper and a TCHES editorial board member

    - were advisee/advisor at any time,
    - have been affiliated to the same institution in the past 2 years,
    - have published 2 or more jointly authored papers in the past 3 years, or
    - are immediate family members.

    For an interpretation of the above reasons, please refer to the IACR policy on CoIs (https://www.iacr.org/docs/conflicts.pdf). Note that conflicts may also arise for reasons other than those just listed. Examples include closely related technical work, cooperation in the form of joint projects or grant applications, business relationships, close personal friendships, instances of personal enmity.

- Full transparency is of utmost importance, authors and reviewers must disclose to the chairs or editor any circumstances that they think may create bias, even if it does not raise to the level of a CoI. At the time of submission, authors are **required** to

    1. make a declaration regarding any conflicts of interest (including reasons for the conflict), and
    2. guarantee they will deliver a presentation at the associated CHES conference if their submission is accepted for publication in TCHES.

- Each paper will be double-blind reviewed by at least four members of the TCHES editorial board.

- In order to improve the quality of the review process, authors are given the opportunity to submit a rebuttal (between the indicated dates) after receiving the associated reviews.

- The review process outcome is either an outright accept or reject decision, or one of two deferred decision types. Specifically, *"minor revision"* means the paper is conditionally accepted, and assigned a shepherd to verify the revision is adequate, *"major revision"* means the authors are invited to submit a revision of their article to one of the following two submission deadlines; a later re-submission will be treated as a new paper.

- When submitting a major revision, follow the instructions in the submission system to indicate that the paper is a major revision and to provide the ID of the earlier submission.

- To ensure consistency, the reviewers assigned for a revised paper are ideally the same as for the original submission.

- Resubmission of papers that have previously been rejected from TCHES is only allowed after major modifications and approval by the Editors-in-Chief prior to submission.

- Authors of submitted papers are also highly encouraged to check the TCHES FAQ

    https://tches.iacr.org/index.php/TCHES/faq

    for answers to questions related to policy and procedures governing CHES.

Contacts

1. Program Co-Chairs / Co-Editors-in-Chief

Diego F. Aranha
Aarhus University, DK

Marcel Medwed
NXP Semiconductors, AT

ches2023programchairs@iacr.org

2. General Co-Chairs

Hana Kubátová & Martin Novotný
Czech Technical University in Prague, CZ

ches2023@iacr.org

3. Artifact Chair

Peter Schwabe
MPI-SP, DE & Radboud University, NL

ches2023artifacts@iacr.org

4. Managing Editor

Tim Güneysu
Ruhr University Bochum, DE

tches-managing-editor@iacr.org

5. Program Committee/Editorial Board

Nele Mentens Leiden University, The Netherlands & KU Leuven, Belgium
Lauren De Meyer Rambus Cryptography Research, The Netherlands
Daniel Moghimi University of California San Diego, USA
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Peter Rindal VISA Research, USA
Thomas Roche NinjaLab, France
Mélissa Rossi ANSSI, France
Sujoy Sinha Roy Graz University of Technology, Austria
Markku-Juhani O. Saarinen PQShield Ltd., UK
Kazuo Sakiyama The University of Electro-Communications, Japan
Pascal Sasdrich Ruhr University Bochum, Germany
Patrick Schaumont Worcester Polytechnic Institute, USA
Georg Sigl Technical University of Munich and Fraunhofer AISEC, Germany
Marcos A. Simplício Jr. University of São Paulo, Brazil
François-Xavier Standaert UCLouvain, Belgium
Rainer Steinwandt University of Alabama in Huntsville, USA
Takeshi Sugawara The University of Electro-Communications, Japan
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Wenjie Xiong Virginia Tech, USA
Yu Yu Shanghai Jiao Tong University, China
Fan (Terry) Zhang Zhejiang University, China